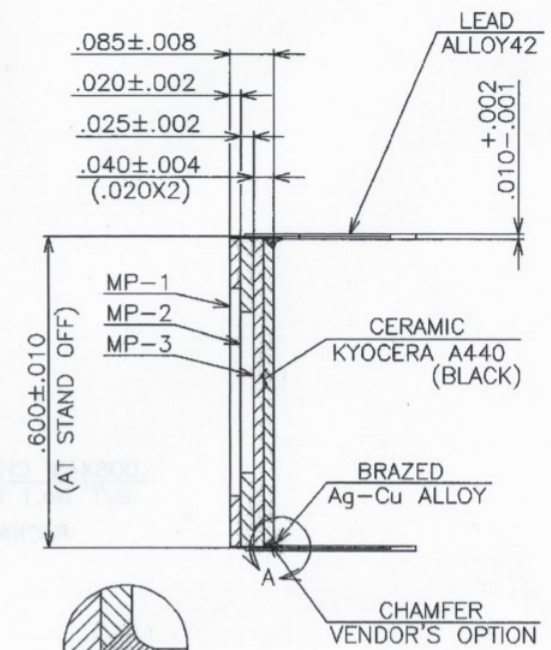
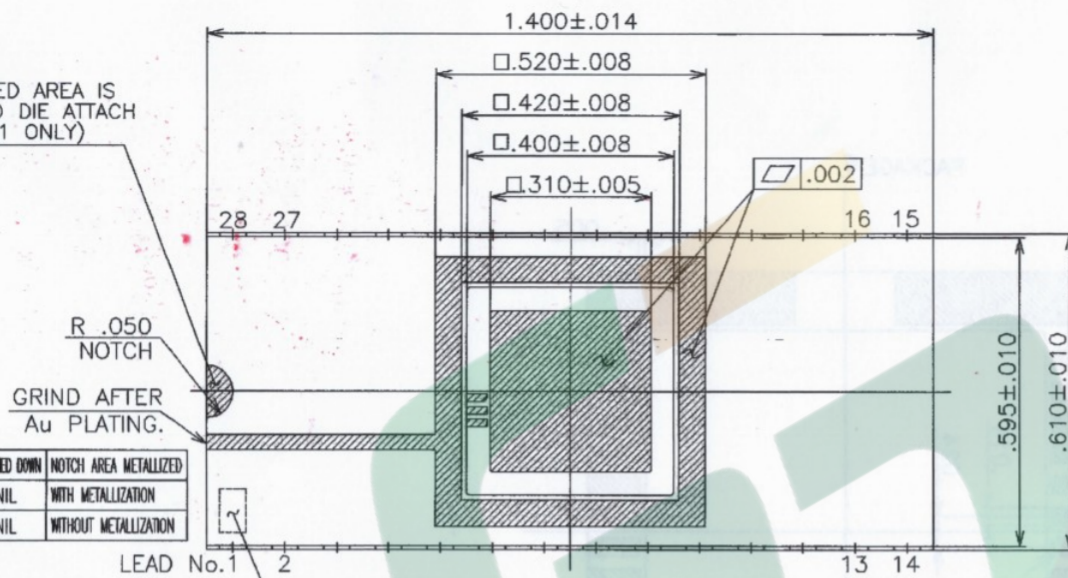


THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD.(PART No.1 ONLY)

PART No.	LD MARK	LEAD TIED DOWN	NOTCH AREA METALLIZED
01		NIL	WITH METALLIZATION
02		NIL	WITHOUT METALLIZATION

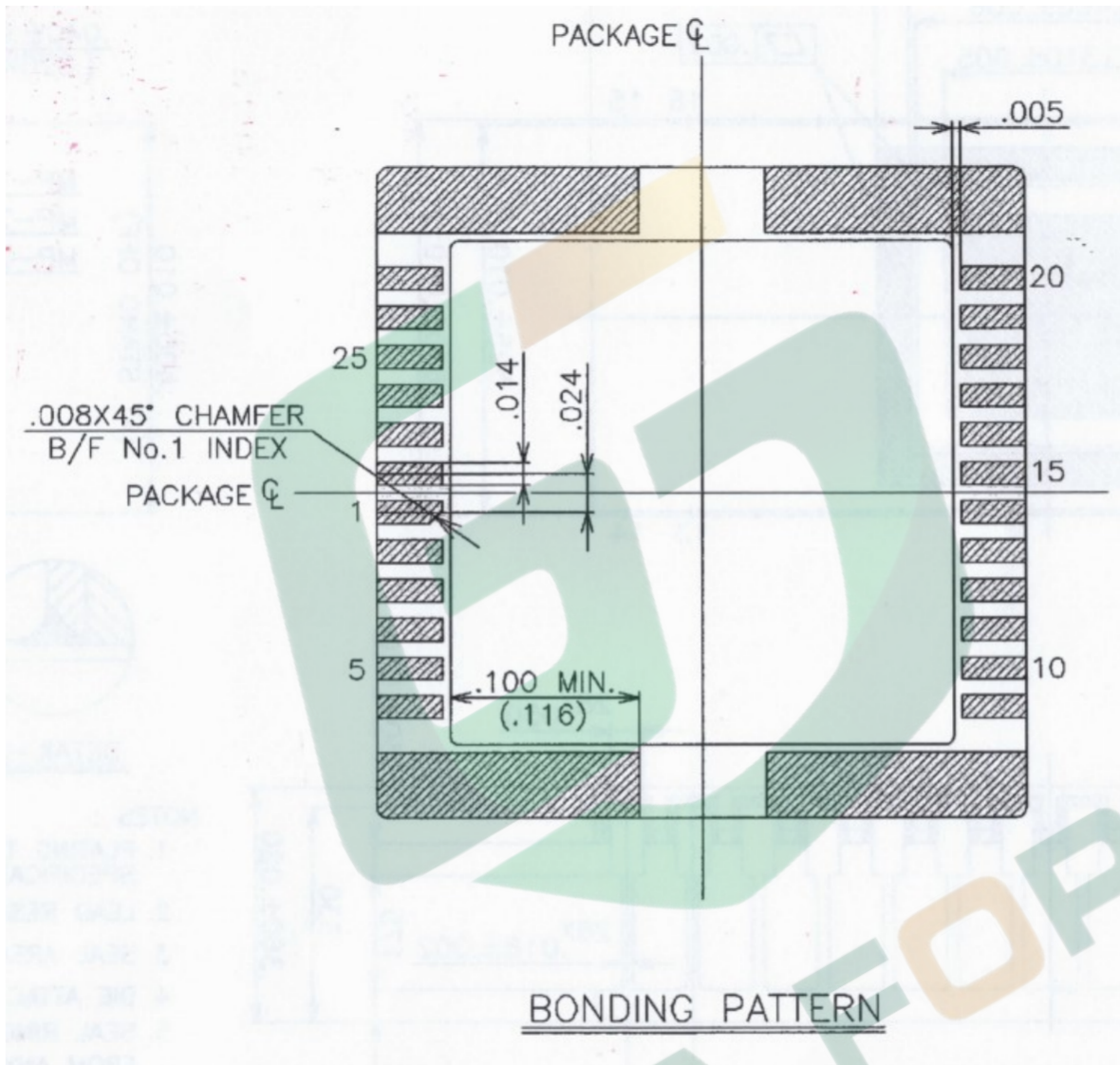


- DETAIL-A
- NOTES :
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. LEAD RESISTANCE : 0.3 OHM MAX.
 3. SEAL AREA TO BE METALLIZED.
 4. DIE ATTACH AREA TO BE METALLIZED.
 5. SEAL RING AND DIE ATTACH TO BE FLOATING FROM ANY PINS.



上海季丰电子科技有限公司
GIGA FORCE ELECTRONICS CO.,Limited

制图	胡熠文	Title	DIP28-F	
核准	何桂港	POD No	POD-SHJF-48	
日期	2023. 1. 31	DIMENSIONS IN:	in	Rev:A



上海季丰电子科技有限公司
GIGA FORCE ELECTRONICS CO., Limited

制图	胡熠文	Title	DIP28-F		
核准	何桂港	POD No	POD-SHJF-48		
日期	2023. 1. 31	DIMENSIONS IN:	in	Rev:A	